MICROCHIP

Semiconductor Device Type: B3X 8 DFN 2x3x0.9mm Matte Tin

Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm
Silicon	7440-21-3	Die	3.21	0.50	32090
Aluminum	7429-90-5	Die	0.01	0.00	112
Tungsten	7440-33-7	Die	0.05	0.01	535
Titanium	7440-32-6	Die	0.00	0.00	9
Copper	7440-50-8	Lead Frame	41.82	6.54	418226
Iron	7439-89-6	Lead Frame	1.01	0.16	10089
Phosphorus	7723-14-0	Lead Frame	0.03	0.01	343
Zinc	7440-66-6	Lead Frame	0.06	0.01	558
Lead	7439-92-1	Lead Frame	0.01	0.00	86
Silver	7440-22-4	Lead Frame Plating	0.52	0.08	5222
Silver	7440-22-4	Die Attach	0.77	0.12	7685
Isobornyl Methacrylate	7534-94-3	Die Attach	0.05	0.01	528
Lauryl Acrylate	2156-97-0	Die Attach	0.05	0.01	528
1,6-Hexanediol Diacrylate	13048-33-4	Die Attach	0.01	0.00	53
N-Methyl-2-Pyrrolidone	872-50-4	Die Attach	0.00	0.00	7
Copper	7440-50-8	Bond Wire (CuPdAu Flash Layers)	0.66	0.10	6583
Palladium	7440-05-3	Bond Wire (CuPdAu Flash Layers)	0.02	0.00	206
Gold	7440-57-5	Bond Wire (CuPdAu Flash Layers)	0.01	0.00	69
Epoxy Resin	Trade secret	Mold Compound	2.46	0.38	24550
Phenol Resin	Trade secret	Mold Compound	1.33	0.21	13257
Silica (Amorphous)A	60676-86-0	Mold Compound	42.72	6.68	427176
Silica (Amorphous)B	7631-86-9	Mold Compound	2.46	0.38	24550
Carbon Black	1333-86-4	Mold Compound	0.15	0.02	1473
Tin	7440-31-5	Lead Finish Plating	2.61	0.41	26064
		TOTALS:	100.00	15.65	1,000,000

15.65 mg Total Mass

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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Package Homogeneous Materials

0.51	**(mg) Total**	**Die**	**% of Total Weight**	**3.27**
	Silicon	7440-21-3	98.00	
	Aluminum	7429-90-5	0.34	
	Tungsten	7440-33-7	1.63	
	Titanium	7440-32-6	0.03	
		Total	**100.00**	
6.72	**(mg) Total**	**Lead Frame**	**% of Total Weight**	**42.93**
	Copper	7440-50-8	97.42	
	Iron	7439-89-6	2.35	
	Phosphorus	7723-14-0	0.08	
	Zinc	7440-66-6	0.13	
	Lead	7439-92-1	0.02	
		Total	**100.00**	
0.08	**(mg) Total**	**Lead Frame Plating**	**% of Total Weight**	**0.52**
	Silver	7440-22-4	100.00	
		Total	**100.00**	
0.14	**(mg) Total**	**Die Attach**	**% of Total Weight**	**0.88**
	Silver	7440-22-4	87.33	
	Isobornyl Methacrylate	7534-94-3	6.00	
	Lauryl Acrylate	2156-97-0	6.00	
	1,6-Hexanediol Diacrylate	13048-33-4	0.60	
	N-Methyl-2-Pyrrolidone	872-50-4	0.08	
		Total	**100.00**	
0.11	**(mg) Total**	**Bond Wire (CuPdAu Flash Layers)**	**% of Total Weight**	**0.69**
	Copper	7440-50-8	96.00	
	Palladium	7440-05-3	3.00	
	Gold	7440-57-5	1.00	
		Total	**100.00**	
7.68	**(mg) Total**	**Mold Compound**	**% of Total Weight**	**49.10**
	Epoxy Resin	Trade secret	5.00	
	Phenol Resin	Trade secret	2.70	
	Silica (Amorphous)A	60676-86-0	87.00	
	Silica (Amorphous)B	7631-86-9	5.00	
	Carbon Black	1333-86-4	0.30	
		Total	**100.00**	
0.41	**(mg) Total**	**Lead Finish Plating**	**% of Total Weight**	**2.61**
	Tin	7440-31-5	100.00	
15.65		**Total**	**100.00**	100.00